

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2607177

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>YEN-PING WANG</td> <td>10/24/2013</td> </tr> <tr> <td>MING-KAI LIU</td> <td>10/24/2013</td> </tr> <tr> <td>KAI-CHIANG WU</td> <td>10/24/2013</td> </tr> </tbody> </table>		Name	Execution Date	YEN-PING WANG	10/24/2013	MING-KAI LIU	10/24/2013	KAI-CHIANG WU	10/24/2013
Name	Execution Date								
YEN-PING WANG	10/24/2013								
MING-KAI LIU	10/24/2013								
KAI-CHIANG WU	10/24/2013								
RECEIVING PARTY DATA									
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.								
Street Address:	No. 8, Li-Hsin Rd. 6								
Internal Address:	Science-Based Industrial Park								
City:	Hsin-Chu								
State/Country:	TAIWAN								
Postal Code:	300-77 R.O.C.								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14074293</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14074293				
Property Type	Number								
Application Number:	14074293								
CORRESPONDENCE DATA									
Fax Number:	(972)732-9218								
Phone:	972-732-1001								
Email:	docketing@slater-matsil.com								
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>									
Correspondent Name:	SLATER & MATSIL, L.L.P.								
Address Line 1:	17950 PRESTON ROAD								
Address Line 2:	SUITE 1000								
Address Line 4:	DALLAS, TEXAS 75252								
ATTORNEY DOCKET NUMBER:	TSM13-0969								
NAME OF SUBMITTER:	ANN TRAN								

Signature:	/Ann Tran/
Date:	11/07/2013
Total Attachments: 1 source=TSM13-0969_Assignment#page1.tif	

ATTORNEY DOCKET NO.  
TSM13-0969

**ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

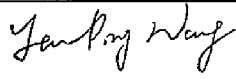

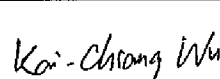
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77 R.O.C. is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<b>Method for Singulating Packaged Integrated Circuits and Resulting Structures</b>			
SIGNATURE OF INVENTOR AND NAME	 Yen-Ping Wang	 Ming-Kai Liu	 Kai-Chiang Wu	
DATE	2013.10.24	2013.10.24	2013.10.24	
RESIDENCE	Hemei Township, Taiwan, R.O.C.	New Taipei City, Taiwan, R.O.C.	Hsin-Chu, Taiwan, R.O.C.	